

PACKAGE STRUCTURE WITH A CAVITY

Abstract

A package structure with a cavity comprises a chip, a multi-layer ceramic substrate, and an adhesive layer. The chip has a circuit disposed thereon and a plurality of first bonding pads disposed around the circuit, and the multi-layer ceramic substrate has a cave formed thereon and a plurality of second bonding pads disposed around the cave wherein the cave and the plurality of second bonding pads are corresponding to the circuit and the plurality of first bonding pads, respectively. The adhesive layer is applied to the surface of the substrate, with the cave and the second pads exposed from the adhesive layer, for tightly bonding the chip and the multi-layer ceramic substrate together such that the circuit of the chip is corresponding to the cave of the multi-layer ceramic substrate so as to form a cavity.

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